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# 会议手册

CONFERENCE MANUAL

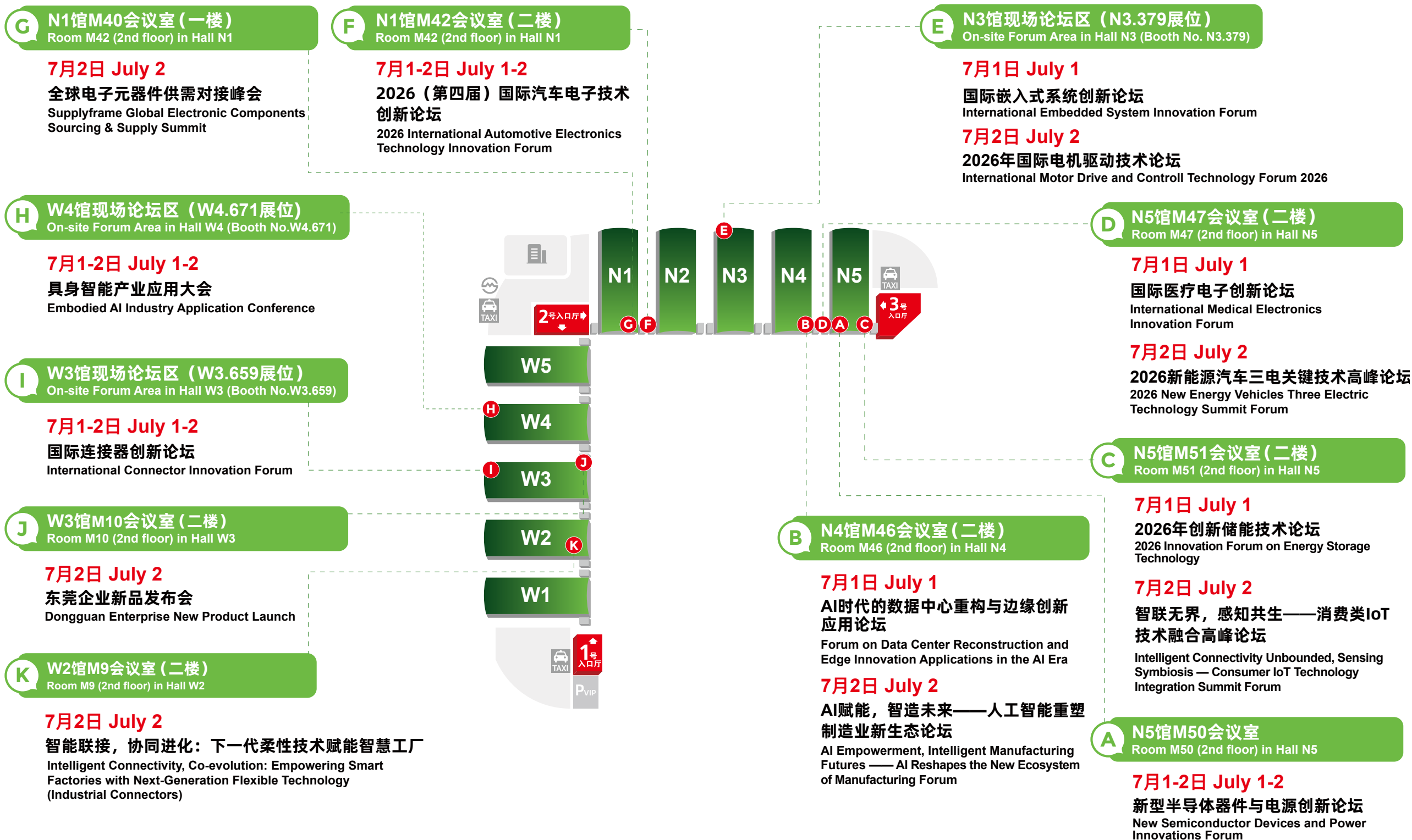
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## 2026 年创新储能技术论坛

### 2026 Innovation Forum on Energy Storage Technology

2026 年 7 月 1 日 | N5 馆 M51 会议室 (二楼)  
July 1, 2026 | Room M51 (2nd floor) in Hall N5

时间 Time	演讲主题 Topic	演讲企业 Speaker
09:00-09:55	签到 & 早到抽奖 Sign in & Lucky draw	
09:55-10:00	主办方致辞 Welcome Speech	张迎辉, 电子发烧友网, 总经理 Mike Zhang, General Manager, Elecfans
10:00-10:30	功率半导体器件在储能行业的产品、应用和趋势 Power Semiconductor Devices for Energy Storage: Products, Applications & Trends	施俊, 扬州扬杰电子科技股份有限公司, 功率器件事业部总经理 David Shi, General Manager of the Power Devices Division, Yangzhou Yangjie Electronic Technology Co., Ltd.
10:30-11:00	德州仪器 (TI) 新一代 EIS 解决方案, 助力探索大容量储能安全监测新界限 Advancing Energy Storage Battery Safety: Next-Generation EIS System Solutions from TI	严骏华, 德州仪器, 系统工程师 Junhua Yan, System engineer, Texas Instruments
11:00-11:30	STM32 在数字能源 PCS 中应用 STM32 in digital energy PCS applications	韩旭同, 意法半导体, 通用 MCU 市场经理 Terry Han, General MCU Market Manager, ST
11:30-12:00	国民技术 MCU 与 BMS 产品: 驱动光储充安全高效运行 NSING MCU & BMS Products: Driving Safe and Efficient Operation in Solar-Storage-Charging Applications	刘亚明, 国民技术, 市场总监 Yaming Liu, Marketing Director, Nations
时间 Time	演讲主题 Topic	演讲企业 Speaker
13:30-14:00	物理 AI 应用实践: 基于瑞萨电子 AI 工具链实现拉弧检测 Physical AI Application Practice: Arc Detection Based on Renesas Electronics AI Toolchain	苏勇, 瑞萨电子, 嵌入式处理器事业部高级系统架构师 Andrew Su, Senior System Architect, Embedded Processing, Renesas Electronics
14:00-14:30	ADI 核心技术在储能系统中的应用与创新实践 ADI Core Technologies in Energy Storage Systems: Applications and Innovative Practices	金城, ADI, 技术支持 Eric Jin, FAE, ADI
14:30-15:00	光伏储能电路设计中兼顾安全可靠与高效的解决方案 Safety and Efficiency Solutions in Solar Energy and Energy Storage Systems	张军, Littelfuse, Inc., 资深应用工程师 Luke Zhang, Senior Application Engineer, Littelfuse, Inc.
15:00-15:30	纳芯微隔离 + 解决方案助力高效、高可靠性光储系统 NOVOSENSE ""Isolation+"" Solutions for Efficient and Highly Reliable PV and Energy Storage Systems Title: System Application Engineer	戴宇峰, 纳芯微, 系统应用工程师 Yufeng Dai, NOVOSENSE, System Application Engineer
15:30-16:00	储能市场分析及行业发展趋势 Analysis of Energy Storage Market and Industry Development Trends	黄山明, 电子发烧友网, 产业分析师 Simon Huang, Industry Analyst, Elecfans
16:00-16:10	抽奖环节	



## 新型半导体器件与电源创新论坛

### New Semiconductor Devices and Power Innovations Forum

2026年7月1日 | N5馆 M50 会议室  
July 1, 2026 | Room M50 (2nd floor) in Hall N5

黄金赞助: **nexperia**

主题: 第三代功率半导体与无源器件

Session: Third-generation Power Semiconductors and Passive Components

主持人: 汤天浩教授, IEEE PELS- 中国电源学会上海联合分部主席

Moderator: Professor TianhaoTang, Chair of IEEE PELS-CPSS Joint Chapter Shanghai

时间 Time	演讲主题 Topic	演讲企业 Speaker
09:00-09:45	签到入场 Registration	
09:45-10:15	氮化镓器件在 AIDC 电源中的应用新范式 A New Paradigm for GaN Devices in AIDC Power Supplies	崔崧博士, 上海宏微爱赛半导体有限公司, 首席技术官 Kevin Cui, CTO, Shanghai MacMic Ai Semiconductor Co., Ltd.
10:15-10:45	英领创新, GaN 有效率 Infineon Leads Innovation with High-efficiency GaN Technology	程文涛, 英飞凌科技消费、计算与通讯业务大中国区氮化镓市场负责人 Winter Cheng, Marketing Head of GaN, Consumer, Computing & Communication Greater China at Infineon Technologies
10:45-11:15	新型功率半导体器件助力电源应用安全和高效 New Power Semiconductor Devices Enhance Safety and Efficiency in Power Supply Applications	刘鹏, Littelfuse 公司, 技术应用经理 Kevin Liu, FAE manager, Littelfuse, Inc.
11:15-11:45	基于 AI 智能算法的高效高功率密度单级 OBC High-efficiency and high-power-density single-stage OBC based on AI intelligent algorithms	陈材, 华中科技大学, 教授 Cai Chen, Full Professor, Huazhong University of Science and Technology
11:45-12:15	AOS 全方位功率半导体方案——驱动高效能与可靠性的未来 AOS Complete Power Semiconductor Portfolio —Where High Efficiency Meets Proven Reliability	游家崧, 万国半导体元件(深圳)有限公司, 高压产品线资深经理 Simon You, Senior Manager of HV Product Line, Alpha and Omega Semiconductor Limited

时间 Time	演讲主题 Topic	演讲企业 Speaker
13:15-13:45	采用新型封装技术的额定电流高达 3000A 的创新型固态断路器功率模块 Novel Solid State Circuit breaker power module up to 3000A in new packaging technology	Norbert Pluschke, 翼同半导体(香港)有限公司, CTO Norbert Pluschke, Chief Technical officer, CN-iCuTechSemiconductor HongKong
13:45-14:15	德州仪器推出业界先进集成 GaN 开关稳压器 TI's integrated GaN switching regulators	郭德胜, 德州仪器, 系统工程师 Desheng Guo, System engineer, Texas instruments
14:15-14:45	功率密度跃迁驱动下一代电源系统演进 Power density and implications for power systems	Dinesh Ramanathan, 安森美, 企业战略高级副总裁 Dinesh Ramanathan, Senior Vice President, Corporate Strategy, onsemi
14:45-15:15	一种应用于开关电源领域的快速响应环路补偿芯片 A fast-response loop compensation IC for application in the switching power supply field	刘建强, RECOM 中国, 高级工程师 Luke Liu, Senior Engineer, RECOM
15:15-15:45	从 Si 到 GaN: 助力数据中心电源能效提升 Si to GaN: Elevating Data Center Power Efficiency	许翔, 英诺赛科, 现场应用总监 Luca Xu, FAE Director, Innoscience
15:45-16:15	带栅极漏电流检测及恒流驱动的主驱动芯片 Advanced Driver IC with IGSS Detection and Constant Current Driving for Traction Inverter Applications	叶忠博士, 瞻芯电子, 首席技术官 Zhong(John) Ye, CTO, InventChip Technology

\* 会议日程请以当天公告为准  
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## 新型半导体器件与电源创新论坛

### New Semiconductor Devices and Power Innovations Forum

2026年7月2日 | N5馆 M50会议室  
July 2, 2026 | Room M50 (2nd floor) in Hall N5

黄金赞助: **nexperia**

#### 上午主题: 新能源变换与电动车驱动技术

##### AM Session: New Energy Conversion and Electric Vehicle Drivetrain Technology

主持人: 蔡旭教授, 上海交通大学

Moderator: Caixu, Professor, School of Electrical Engineering, Shanghai Jiao Tong University

时间 Time	演讲主题 Topic	演讲企业 Speaker
09:00-10:00	签到入场 Registration	
10:00-10:30	构建主力电源型新能源的关键技术与实践 Key Technologies and Practices for Building Main Power Supply-Type New Energy Sources	蔡旭教授, 上海交通大学电气工程学院, 教授 Caixu, Professor, School of Electrical Engineering, Shanghai Jiao Tong University
10:30-11:00	绿色 AI 时代的推手: 从硅到宽能隙的功率半导体演进 Enabling Green AI: The Evolution of Power Semiconductors from Silicon to Wide Bandgap	林橙宽, 海驰科技股份有限公司, 总经理 Stanley Lin, CEO, AzureMoto Technology, Inc.
11:00-11:30	60 千瓦电动汽车直流充电桩数字电源解决方案 60 kW digital power solutions for DC charging piles of electric vehicles	胡庆, 意法半导体应用工程师 Leon Hu, Application Engineer, STMicroelectronics
11:30-12:00	迈向零碳交通 - 车载电化学复合电源及其能源供给 Towards Zero-Carbon Transportation: Onboard Electrochemical Hybrid Power Supply and Its Energy Provision	戴海峰教授, 同济大学, 教授 HaifengDai, Professor, Tongji University

#### 下午主题: 人工智能和数据中心电源技术

##### PM Session: Artificial Intelligence and Data Center Power Technologies

主持人: 傅旻帆, 上海科技大学, 研究员

Moderator: MinfanFu, Associate Professor, ShanghaiTechUniversity

时间 Time	演讲主题 Topic	演讲企业 Speaker
13:00-13:30	AI 数据中心供电架构的演进趋势 Evolution Trends of Power Supply Architecture in AI Data Centers	侯召政, 华为技术有限公司, 华为数字能源技术与平台规划部部长 Zhaozheng Hou, Director, Technology & Platform Strategy Dept., Huawei Digital Power, Huawei Technologies Co., Ltd.
13:30-14:00	系统级电源创新驱动 AI 算力与电气化新纪元 Power Solutions that Scale AI Datacenters and Accelerate Electrification	Biljana Beronja, 安森美, 电源方案事业部碳化硅产品线负责人 Biljana Beronja, onsemi PSG Elite SiC Business Unit Management
14:00-14:30	小器件守护大数据中心 - 安世高可靠电源管理和供应链自主技术解析 Small IC, Guardians of Big Data Centers - Nexperia's High-Reliability Power Management and Supply Chain Independence	李林凯, 安世半导体(中国)有限公司, IC 解决方案事业部系统应用经理 Linkai Li, ICS BC System manager, Nexperia Semiconductors (China) Ltd.
14:30-15:00	AI 设施快速成长下, 功率半导体产业的新布局 New Strategy of the Power Semiconductor Industry Driven by the Rapid Growth of AI Infrastructure	姚明立, 美微科半导体有限公司, 高级产品经理 Yew Ming Lik, Senior Product Manager, Micro Commercial Components
15:00-15:30	数据中心 800VDC 供电架构与案例实践 800V DC Power Supply Architecture & Practice for Data Centers	张彦和, 台达, 高级工程师、台达 - 中达电通技术支持部总监 Zhang Yanhe, SE, Delta
15:30-16:00	算力时代数据中心供电架构演进与最新趋势 Evolution of Power Supply Architectures and Latest Trends in Data Centers in the Computing Power Era	傅旻帆, 上海科技大学, 研究员 MinfanFu, Associate Professor, ShanghaiTech University

\*会议日程请以当天公告为准

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07/01

B

## AI 时代的数据中心重构与边缘创新应用论坛

### Forum on Data Center Reconstruction and Edge Innovation Applications in the AI Era

2026 年 7 月 1 日 | N4 馆 M46 会议室 (二楼)  
July 1, 2026 | Room M46 (2nd floor) in Hall N4

时间 Time	演讲主题 Topic	演讲企业 Speaker
09:00-09:55	观众签到 Audience check-in	
09:55-10:00	主持人开场	深圳市智博数字信息技术有限公司 Shenzhen Zhibo Digital Information Technology Co., Ltd
10:00-10:30	向未来的 AI 算力：云原生、绿色计算与芯片应用新架构 Future-Oriented AI Compute: Cloud-Native, Green Computing, and New Chip Application Architectures	王侃頔，华为云计算技术有限公司，华为云解决方案架构专家 Wang Kanjie, Cloud Solution Architecture Expert, Huawei Cloud Computing Technologies Co., Ltd.
10:30-11:00	具身智能的算力下沉：从云端依赖到边缘自主的进化之路 Embodied AI Computing Downlink: The Evolutionary Path from Cloud Dependency to Edge Autonomy	刘金明，节卡机器人，具身智能产品负责人行业总监 Liu Jinming, Head of Intelligent Products for Jieka Robot Body, Industry Director, Improving English Translation
11:00-11:30	具身智脑技术挑战与发展思路 - 灵境智源边缘侧计算平台 Technical Challenges and Development Strategy for Embodied AI Brains - MScapedge-Side Computing Platform	李智垠，上海灵境智源科技有限公司，泛具身销售经理 Li Zhiyin, Sales Manager, Shanghai MScape Technology Co., Ltd.
11:30-12:00	大模型加持的具身智能，助力智能制造转型升级 Embodied AI Powered by Large Language Models to Drive the Transformation and Upgrade of Smart Manufacturing	周闻钧，广州智用开物人工智能科技有限公司，首席技术官，联合创始人 Zhou Wenjun, CTO & Co-founder, Guangzhou Smartify Open Technology Co., Ltd.
12:00-13:30	午餐 / 观展 / 嘉宾入场 / 签到 Lunch break	

时间 Time	演讲主题 Topic	演讲企业 Speaker
13:30-14:00	算力底座再升级：分布式存储系统如何支撑 AI 数据中心高速演进 Upgrading the Computing Infrastructure: How Distributed Storage Systems Drive the Rapid Evolution of AI Data Centers	刘帅，中科曙光，华南区运营总监 Liu Shuai, Operations Director (South China), Dawning Information Industry Co., Ltd. (Sugon)
14:00-14:30	云端与指尖的共舞：重塑 AI 时代的算力版图 Dance of Cloud and Fingertips: Reshaping the Computing Landscape in the AI Era	弋方，恩智浦半导体，高级市场经理 Yi Fang, Sr. Marketing Manager, NXP
14:30-15:00	224G 到 448G 高速互连技术解决方案探究 Exploration of 224G to 448G High-Speed Interconnect Technology Solutions	袁俊峰，中航光电科技股份有限公司，技术总监 Junfeng Yuan, Technical Director, AVIC JONHON Optron Technology Co.,Ltd
15:00-15:30	智慧物流新基建：边缘算力如何重塑供应链网络 Smart Logistics New Infrastructure: How Edge Computing Reshapes Supply Chain Networks	卢杰，顺丰科技有限公司，解决方案专家 Lu Jie, Solution Expert, S.F. Technology Co., Ltd.
15:30-16:00	AI 算力基石：系统架构与核心功率器件趋势 Backbone of AI Computing: System Architecture and Core Power Device Trends	许广通，扬州扬杰电子科技股份有限公司，FAE 应用总监 Mark Xu, FAE Application Director, Yangzhou Yangjie Electronic Technology Co., Ltd.
16:00-17:00	现场交流 / 观展	

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07/02  
B

## AI 赋能，智造未来 ——人工智能重塑制造业新生态论坛

### AI Empowerment, Intelligent Manufacturing Futures —— AI Reshapes the New Ecosystem of Manufacturing Forum

2026 年 7 月 2 日 | N4 馆 M46 会议室 (二楼)  
July 2, 2026 | Room M46 (2nd floor) in Hall N4

上午主题：智造基石 :AI 技术引擎与工业数字底座

AM Session: The Bedrock of Smart Manufacturing: AI Engines and Industrial Digital Infrastructure

时间 Time	演讲主题 Topic	演讲企业 Speaker
09:00-10:00	签到入场 Registration	
10:00-10:05	领导致辞 Opening Remarks	张浩, 上海市人工智能学会, 理事长、同济大学 CIMS 研究中心, 教授 Zhang Hao, Chairman of the Shanghai Society of Artificial Intelligence, Professor at the CIMS Research Center of Tongji University.
10:05-10:30	具身智能与人形机器人场景应用 Embodied intelligence and humanoid robot scene applications	朱文华, 浦江学者、俄罗斯自然科学院, 院士、上海嘉定菊园未来数智研究院, 院长、教授 Zhu Wenhua, Pujiang Talent, Distinguished Professor, Academician of the Russian Academy of Natural Sciences, Dean of the Shanghai Jiading Juyuan Research Institute of Future Digital Intelligence.
10:30-11:00	智能制造的得力助手, 从机械臂到机器人 A capable assistant for smart manufacturing, from robotic arms to robots	冯国柱, 意法半导体策略市场经理 Robin Feng, Strategic Marketing Manager, STMicroelectronics
11:00-11:30	边缘 AI 助力工业数字底座 Edge AI Empowers The Industrial Digital Foundation	弋方, 恩智浦半导体, 高级市场经理 YiFang, Sr. Marketing Manager, NXP
11:30-12:00	工业具身多模态数据采集及应用 Industrial Embodied Multimodal Data Acquisition and Applications	陈国栋, 苏州大学机电工程学院, 博士生导师、教授 Chen Guodong, Professor and Doctoral Supervisor, School of Mechanical and Electric Engineering, Soochow University.

下午主题：生态融合：AI 驱动的工业场景革命与价值链重塑

PM Session: Ecosystem Integration: The AI-Driven Industrial Revolution and Reimagining the Value Chain

时间 Time	演讲主题 Topic	演讲企业 Speaker
13:00-13:30	签到入场 Registration	
13:30-14:00	驱动优化工具实现 AI 智能仿真世界 Optimization Tools Drive an AI-Powered Intelligent Simulation World	曾家麟, 莎益博工程系统开发 (上海) 有限公司, 技术总监 Ben.tseng PhD, Technical Director, CYBERNET SYSTEMS (SHANGHAI) CO., LTD.
14:00-14:30	TI 创新技术赋能更安全、更智能的下一代智慧工厂 TI's innovative technologies enable safer and smarter next generation smart factories	高晨, 德州仪器半导体技术 (上海) 有限公司, 系统工程师 Chen Gao, System Engineer, Texas Instruments Semiconductor Technologies (Shanghai) Co., Ltd.
14:30-15:00	开放生态·AI 驱动: vPLCnext 构建 IOT 融合的虚拟控制底座 Open Ecosystem · AI-Driven: vPLCnext Builds a Virtual Control Foundation for IoT Convergence	孙涛, 菲尼克斯电气, PLCnext 软件生态产品经理 Lucas Sun, PLCnext Software Ecosystem & Business Product Management, Phoenix Contact
15:00-15:30	打通工业与校园: 易盼完整生态及电气设计竞赛发展之路 Connecting Industry and Academia: The Complete Ecosystem of Eplan & The Development Journey of Electrical Design Competitions	卫玮, 易盼软件 (上海) 有限公司, 资深技术顾问 Tommy Wei, Senior Technical Consultant, EPLAN Software (Shanghai) Co., Ltd.
15:30-16:00	“脑体协同” —— 具身智能重塑行业应用新范式 “Brain-Body Collaboration” : Embodied Intelligence Redefining a New Paradigm for Industrial Applications	张敏, 联想研究院机器人实验室, 方案架构总监、主任工程师 Myron Zhang, Director of Solution Architecture and Principal Engineer, Robotic Lab, Lenovo Research

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07/02  
C

## 智联无界，感知共生 ——消费类 IoT 技术融合高峰论坛

Intelligent Connectivity Unbounded, Sensing Symbiosis  
— Consumer IoT Technology Integration Summit Forum

2026 年 7 月 2 日 | N5 馆 M51 会议室 (二楼)  
July 2, 2026 | Room M51 (2nd floor) in Hall N5

上午场：技术基座 —— “感知” 与 “算力” 的物理世界入口  
Morning Session: Technology Foundation - The Physical Gateway to “Sensing” and “Compute”

时间 Time	演讲主题 Topic	演讲企业 Speaker
09:15-09:45	签到入场 Registration	
09:45-10:00	开幕致辞 / Opening Remarks 《从“互联”到“共智”：2026 消费 IoT 的产业拐点》 From “Connectivity” to “Collective Intelligence” : The Inflection Point of Consumer IoT in 2026	主办方 Organizer
10:00-10:30	主题演讲 1 / Keynote 1 ExecuTorch 在 Arm 架构上的实现 ExecuTorch on Arm	杨瑞，安谋科技中国有限公司，高级嵌入式市场经理 Eric Yang, Senior Marketing Manager, Arm China Technology
10:30-11:00	主题演讲 2 / Keynote 2 《感知·连接·智算·安全：英飞凌系统级方案助力智能眼镜乘势而上》 Perception · Connection · Intelligent Computing · Security: Infineon’s System-level Solutions Enable the Accelerated Development of Smart Glasses	张庆峰，英飞凌科技消费、计算与通讯业务大中华区，市场总监 Rick Zhang, Marketing Director, Consumer, Computing & Communication Greater China at Infineon Technologies
11:00-11:30	主题演讲 3 / Keynote 3 《从“连接器”到“智算中枢”：AI 模组如何重构消费 IoT 的算力基座》 From “Connector” to “Intelligent Computing Hub” : How AI Modules Are Redefining the Computing Foundation of Consumer IoT	上海移远通信技术股份有限公司 Quectel Wireless Solutions Co., Ltd.
11:30-12:00	主题演讲 4 / Keynote 4 《感知无界：传感器技术如何重塑消费 IoT 体验》 Boundless Sensing: How Sensor Technology is Reshaping the Consumer IoT Experience	曹煌，深圳麦乐克传感技术有限公司 华东地区负责人 Cao Huang, East China Regional Head, Shenzhen Melrose Sensing Technology Co., Ltd.

下午场：场景落地 —— “连接” 与 “智能” 的无界体验  
Afternoon Session: Scenario Implementation - The Boundless Experience of “Connectivity” and “Intelligence”

时间 Time	演讲主题 Topic	演讲企业 Speaker
14:00-14:05	主持人开场 Host Introduction	
14:05-14:25	主题演讲 5 / Keynote 5 《给 AI 以“心跳”：高精度晶振在 AIGC 与高速互联中的关键角色》 Giving AI a “Heartbeat” : The Critical Role of High-Precision Crystals in AIGC and High-Speed Interconnect	孙刚，深圳市晶科鑫实业有限公司，总经理 Sun Gang, General Manager, Shenzhen SJK Industrial Co., Ltd.
14:25-14:45	主题演讲 6 / Keynote 6 《端侧 AI 的“芯”基座：高性能模拟 IP 如何赋能消费 IoT 感知与互联》 The “Silicon” Foundation of Edge AI: How High-Performance Analog IP Empowers Consumer IoT Sensing and Connectivity	灿芯半导体 (上海) 股份有限公司 Brite Semiconductor (Shanghai) Co., Ltd.
14:45-15:05	主题演讲 7 / Keynote 7 《从“被动响应”到“主动智能”：美的全屋智能的 AI 进化之路》 From “Passive Response” to “Proactive Intelligence” : Midea’s AI Evolution in Whole-Home Intelligence	美的全屋智能 Midea Whole-Home Intelligence
15:05-15:25	主题演讲 8 / Keynote 8 《云端觉醒：AI 智能体在 IoT 中的决策逻辑》 Cloud Awakening: The Decision-Making Logic of AI Agents in IoT	张金繁，阿里云计算有限公司 Zhang Jinfan, Alibaba Cloud Computing Co., Ltd.
15:25-15:45	主题演讲 9 / Keynote 9 《从“穿戴”到“无感”：AI 眼镜如何重构个人智能交互入口》 From “Wearable” to “Seamless” : How AI Glasses Are Redefining the Gateway to Personal Intelligent Interaction	石庆，深圳亿境虚拟现实技术有限公司，总经理 Shi Qing, General Manager, Shenzhen Emdoor VR Technology Co., Ltd.
15:45-16:30	圆桌对话 / Panel Discussion 《产业链对话：从芯片到元器件的 IoT 供应链新格局》 Industry Chain Dialogue: The New Chess Game of the IoT Supply Chain - From Chips to Components	原厂、芯片分销、被动元器件各企业代表 Representatives from OEMs, Chip Distributors, and Passive Component Manufacturers



## 国际医疗电子创新论坛

### International Medical Electronics Innovation Forum

2026年7月1日 | N5馆 M47会议室 (二楼)  
July 1, 2026 | Room M47 (2nd floor) in Hall N5

上午主题: 脑机接口技术: 现状、挑战与未来趋势

AM Session: Brain-Computer Interface Technology: Current Status, Challenges, and Future Trends

主持人: 赵俊, 上海交通大学, 教授, 博导

The MC: Professor Zhao Jun, Shanghai Jiao Tong University

时间 Time	演讲主题 Topic	演讲企业 Speaker
09:15-10:00	签到入场 Registration	
10:00-10:30	经颅超声刺激的神经理调控效应及应用 The neuromodulation effects and applications of transcranial ultrasound stimulation	孙俊峰, 上海交通大学, 教授 Junfeng Sun, Professor, Shanghai Jiao Tong University
10:30-11:00	TI 在 EEG 医疗与 BCI 交互的完整系统方案 TI's Comprehensive System Solution for Medical EEG and BCI Interaction	杨思彦, 德州仪器, TI 现场应用工程师 SiyanYang, TI Field Applications Engineer, Texas Instruments
11:00-11:30	侵入式脑机接口芯片 Integrated Circuits for Invasive Brain-Machine Interface Applications	刘骁, 复旦大学, 教授、博导, 国家海外高层次人才青年项目获得者 LIU XIAO, Professor, Fudan University
11:30-12:00	植入式脑脊接口技术助力瘫痪者重新行走 Implantable Brain-Spinal Interface Technology Facilitates Locomotor Recovery in Paralyzed Individuals	加福民, 神复健行(上海)医疗器械有限公司, 创始人; 复旦大学, 副研究员 Fumin Jia, Associate Researcher/Founder, Wiraxon(Shanghai) Medical Device Co., Ltd.

下午主题: 医疗机器人与创新医疗设备

PM Session: Medical Robots and Innovative Medical Devices

主持人: 上海市生物医学工程学会副理事长, 严壮志教授

The MC: Professor Zhuangzhi Yan, Vice President of Shanghai Biomedical Engineering Society

时间 Time	演讲主题 Topic	演讲企业 Speaker
13:00-13:30	柔性机器人与具身智能 Flexible Robots and Embodied Intelligence	高安柱, 上海交通大学, 教授 Anzhu Gao, Professor, Shanghai Jiao Tong University
13:30-14:00	半导体技术赋能便携式医疗 Semiconductor Technologies Empowers Portable Medical Devices	赵明智, 英飞凌科技消费、计算与通讯业务大中华区, 市场经理 Mingzhi Zhao, Marketing Manager, Consumer, Computing & Communication Greater China at Infineon Technologies
14:00-14:30	面向外科手术中决策支持的电阻抗谱与电阻抗断层成像技术 Electrical impedance spectroscopy and tomography for intra-operative surgeon feedback	俞毅刚, ADI, 亚太区高级应用经理 Hugh Yu, Senior Application Manager, ADI
14:30-15:00	智能手术机器人——水刀与 AI 的融合及其在前列腺增生手术中的应用 Intelligent Surgical Robotics: The Fusion of Waterjet Robot System and AI in the BPH Treatment	陈文波, 北京智愈医疗科技有限公司, CTO Chen Wenbo, CTO, Healinno Tech
15:00-15:30	心腔内超声成像: 从需求到创新 Intracardiac Echocardiography: From Clinical Needs to Technological Innovation	毛佳炜, 上海微创电生理医疗科技股份有限公司, 研发总监 Mao Jiawei, R&D Director, Shanghai MicroPort EP MedTech Co., Ltd.
15:30-16:00	精控每一处关节, 先楫芯片助力医疗机器人迈向高精度时代 HPMicro Empower Medical Robots for High-precision Evolution	曾劲涛, 上海先楫半导体科技有限公司, 董事长, CEO Jintao Zeng, Chairman & CEO, HPMicro Semiconductor Co., Ltd.



## 2026 新能源汽车三电关键技术高峰论坛

### 2026 New Energy Vehicles Three Electric Technology Summit Forum

2026年7月2日 | N5馆 M47会议室 (二楼)  
July 2, 2026 | Room M47 (2nd floor) in Hall N5

主持人: 周正如, OE 汽车, 总经理

Moderator: Zhengru, Zhou, General Manager, Shanghai OE Automotive Tech Co., Ltd.

时间 Time	演讲主题 Topic	演讲企业 Speaker
10:00-10:10	主办方致辞 The organizer speech	周正如, OE 汽车, 总经理 Tim Zhou, GM, OE Auto
10:10-10:40	归元平台重构新能源动力的底层逻辑 GWM-ONE: Reconstructing the Underlying Logic of New Energy Powertrains	刘志刚, 长城汽车混合动力系统主任工程师 Jack Liu, Principal Engineer of Hybrid Powertrain System, Great Wall Motor
10:40-11:10	迈来芯传感器在电驱动应用中的演变 The evolution of Melexis sensors in EV powertrain	吴大鹏, 迈来芯, 区域市场经理 Dapeng Wu, Regional Marketing Manager, Melexis
11:10-11:40	新技术趋势下电驱动系统测评关键技术研究 Research on Key Evaluation Technologies of Electric Drive Systems Under New Technology Trends	邱子桢博士, 中汽研新能源汽车检验中心(天津)有限公司, 电驱电控部高级工程师 Dr. Qiu Zizhen, Senior Engineer, Electric Drive and Electronic Control Department, CATARC New Energy Vehicle Inspection Center (Tianjin) Co., Ltd.
11:40-12:10	待定 TBD	邀请中 TBC
12:10-13:30	午餐 Lunch	

时间 Time	演讲主题 Topic	演讲企业 Speaker
13:30-14:00	电池包多面冷却性能研究 Research on Multi-Surface Cooling Performance of Battery Pack	单炯毅, 泛亚汽车技术中心, 电池热管理及零部件开发技术经理 Jiongyi Shan, Technical Manager, Battery Thermal Management and Component Development, Pan Asia Technical Automotive Center (PATAC)
14:00-14:30	重塑电动汽车驾乘体验的三大半导体技术 3 semiconductor technologies redefining the EV experience	邹立宇, 德州仪器, 系统经理 Liyu Zou, System Manager, Texas Instruments
14:30-15:00	新能源汽车基于回路被动保护解决方案及应用解析 Automotive electronics passive protection solution and application	俞宜锴, Littelfuse, Inc., 产品应用工程经理 Daniel Yu, FAE Manager, Littelfuse, Inc.
15:00-15:30	电动汽车规模化应用背景下, 高功率快充技术解决方案 Unlocking EV Scalability: Breakthrough High-Power Fast Charging Solutions	宋春来, 安波福, 产品工程高级经理、技术专家 Zero Sung, Senior Product Engineering Manager & Technical Expert, APTIV
15:30-16:00	新能源驱动电机绝缘系统发展趋势及挑战 Trends and Challenges in Insulation Systems for EV Traction Motors	魏雄强, 华域汽车电动系统有限公司, 技术中心创新主任 / 高级专家 Xiongqiang Wei, Director of Innovation / Senior Expert, Technology Center, HASCO Automotive
16:00-16:30	待定 TBD	

\*会议日程请以当天公告为准  
The meeting agenda is subject to the announcement on the day.



## 国际嵌入式系统创新论坛

### International Embedded System Innovation Forum

2026年7月1日 | N3馆现场论坛区 (N3.379展位)  
July 1, 2026 | On-site Forum Area in Hall N3 (Booth No. N3.379)

#### 上午主题：嵌入式人工智能技术与应用

##### AM Session: Embedded AI Technology and Applications

主持人：何小庆，嵌入式系统联谊会，秘书长

Moderator: ALLAN HE, Secretary in Chief, Embedded System Associations

时间 Time	演讲主题 Topic	演讲企业 Speaker
09:30-10:00	签到入场 Registration	
10:00-10:30	Arm 平台上的 Zephyr: 从 Cortex-M 扩展到 Cortex-A, 助力边缘人工智能 Zephyr on Arm: Scaling from Cortex-M to Cortex-A for Edge AI	范子莹, 安谋科技, 资深市场经理 (Edge Computing) Jacy Fan, Senior Marketing Manager, Edge Computing, Arm China
10:30-11:00	STM32 Bluetooth® LE 在工业 AIoT 中的应用 STM32 Bluetooth® LE usage in the Industrial AIoT Applications	陈德勇, 意法半导体, 中国区微控制器、数字 IC 与射频产品部 STM32 无线产品线总监 Donald CHAN, STM32 Wireless Products Marketing Director, China Region, STMicroelectronics
11:00-11:30	一种应用于开关电源领域的快速响应环路补偿芯片 A fast-response loop compensation IC for application in the switching power supply fie	刘建强, RECOM 中国, 高级工程师 Luke Liu, Senior Engineer, RECOM
11:30-12:00	嵌入式人工智能技术与应用 Embedded Artificial Intelligence Technology and Applications	徐永龙, 博诚经纬集团, 研究院院长兼首席科学家, 工学博士, 教授级高级工程师, 国家高层次人才 Michael XU, Director and Chief Scientist of the Research Institute, Doc-Ing., Professor-level Senior Engineer, Bothon Longi-lati Group

#### 下午主题：工业物联网技术与生态建设

##### PM Session: Industrial Internet of Things Technology and Ecosystem

主持人：胡晓柏，北京航空航天大学出版社有限公司，副编审

Moderator: Xiaobo Hu, Editor, Beihang University Press

时间 Time	演讲主题 Topic	演讲企业 Speaker
13:00-13:30	基于开源 Coral NPU 的嵌入式 AI 技术与应用 Embedded AI Technology and Application Based on Open-Source Coral NPU	周剑扬, 厦门大学, 教授 Jiayang Zhou, Professor, Xiamen University
13:30-14:00	突破研发瓶颈, 加速产品上市——ADI 在仪器仪表应用中的系统级解决方案 From Design Challenges to Faster Launches: ADI's System-Level Solutions for Instrumentation	姜海涛, ADI 仪器仪表事业部, 高级市场经理 Steven Jiang, Senior Marketing Manager, ADI Instrumentation System Solutions Unit
14:00-14:30	构建端侧智能技术生态, 激活产业 AI 落地 Building Edge Intelligence Ecosystems to Accelerate Scalable AI Deployment Across Industries	施灵峰, 瑞萨电子, 嵌入式处理器事业部市场部高级经理 Lingfeng Shi, Sr. Manager, Embedded Processing, Renesas electronics
14:30-15:00	后摩尔时代的边缘侧人工智能计算 Edge AI Computing in the Post-Moore Era	哈亚军, 上海科技大学, 教授 Yajun Ha, Professor, Shanghai Tech University
15:00-15:30	MIPS: 破局物理 AI 效率壁垒, 赋能 IoT 至车载全场景 AI 高效部署 MIPS: Unlocking Extreme Efficiency in Physical AI with RISC-V	李勇, MIPS (格罗方德旗下公司), 中国区业务发展负责人 Alan Li, China Head of Business Development, MIPS, a GlobalFoundries Company
15:30-16:00	嵌入式系统产业现状与 RISC-V 发展趋势 Current Status of the Embedded System Industry and RISC-V Development Trends	何小庆, 嵌入式系统联谊会, 秘书长 ALLAN HE, Secretary-General, Embedded System Association

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## 2026 (第四届) 国际汽车电子技术创新论坛

2026 International Automotive Electronics Technology Innovation Forum

2026年7月1日 | N1馆 M42会议室 (二楼)  
July 1, 2026 | Room M42 (2nd floor) in Hall N1白金赞助:  dioo  伊世智能 黄金赞助:  W Tech  Sunlord expert in e components  nexperia

主题: 智能座舱

Session: Autonomous Driving

主持人: 杨永喆, 长城汽车技术中心, 技术品牌与规划总监

Moderator: Jared Yang, Director of Technology Strategy, Great Wall Motor R&amp;D Centre

时间 Time	演讲主题 Topic	演讲企业 Speaker
09:00-09:45	签到入场 Registration	
09:45-10:15	软硬云一体化: AI 原生架构重构智能座舱体验 Software-hardware-cloud integration: an AI-native architecture redefines the smart cockpit experience.	唐焱, 博泰车联网科技(上海)股份有限公司, 研发总监 Tang Yan, R&D Director, PATEO CONNECT Technology (Shanghai) Corporation
10:15-10:45	区域式架构下的汽车分布式音频解决方案 Distributed audio solution based on zonal architecture	何蓓薇, 意法半导体应用工程师 BeiWei HE, Application Engineer, STMicroelectronics
10:45-11:15	芯桥梁·新生态: DIA36600 开启车规级 eUSB2 Repeater 新时代 Core Bridge · New Ecosystem: DIA36600 Ushers in a New Era of Automotive-Grade eUSB2 Repeater	庄华龙, 江苏帝奥微电子股份有限公司, 高功率电源产品事业部副总裁 Leon Zhuang, High power product BU VP, Diao Microcircuits Co., Ltd. Jiangsu
11:15-11:45	半导体分立器件在汽车智能座舱中的应用 Application of Semiconductor Discrete Devices in Automotive Smart Cockpits	朱国伟, 扬州扬杰电子科技股份有限公司, 汽车电子市场副总监 Will Zhu, Associate Director of Automotive Electronics Marketing, Yangzhou Yangjie Electronic Technology Co., Ltd.
11:45-12:15	全景视界·交互重构——大画幅 AR-HUD 的客户价值升维 Panoramic Vision, Interaction Redefined — Value Ascension of Large-Format AR-HUD	梁品, 上海浦创汽车科技有限公司, HUD 事业部总经理 Pin Liang, General Manager of HUD Business Unit, Shanghai Puchuang Auto Technology Co.,Ltd.

时间 Time	演讲主题 Topic	演讲企业 Speaker
13:15-13:45	车载电源管理产品技术趋势及安波福解决方案 Driving Efficiency: Next-Generation Low-Voltage Power Management Trends & Aptiv Solutions	杨润杰, 安波福中央电气(上海)有限公司, 电源管理产品经理 Yang Runjie, Power Management Product Line Manager, Aptiv Electrical Centers (Shanghai) Co., Ltd.
13:45-14:15	架构的下一站——智能边缘如何重塑软件定义汽车 The Intelligence Hiding at the Edge — A Preview	Henri-Xavier Delecourt, 安森美模拟与混合信号事业部以太网专家 Henri-Xavier Delecourt, onsemi AMG ethernet expert
14:15-14:45	AI 智能体驱动座舱信息安全风险应对 AI Agent-Driven Handling of Cybersecurity Risks in Connected Cockpits	孙腾野, 上海伊世智能科技有限公司, 事业部总监 Tagg Sun, BU Director, Shanghai UniSentry Intelligent Technology Co., LTD
14:45-15:15	顺络电子: 赋能智能驾舱的创新与变革 Sunlord Electronics: Innovation & Transformation Empowering Intelligent Cockpits	吴少龙, 深圳顺络电子股份有限公司, 厦门分公司总经理 Eric Wu, General Manager of Xiamen Branch, Shenzhen Sunlord Electronics Co.,Ltd.
15:15-15:45	S32K5: 恩智浦面向软件定义汽车的区域控制(Zonal)架构解决方案 NXP S32K5 MCU Family Empower the SDV Zonal Architectures	邓尚超, 恩智浦半导体, 恩智浦大中华区软件定义汽车和边缘 AI 市场负责人 Vincent Deng, Lead of NXP SDV and Edge AI Marketing and BD, Great China, NXP
15:45-16:15	安世半导体: 构建智能座舱的可靠基石 Nexperia: Building a reliable foundation for the smart cockpit	张定一, 安世半导体(中国)有限公司, 资深 FAE 经理 Edward Zhang, Senior FAE manager, Nexperia Semiconductors (China) Ltd.
16:15-16:45	华勤星轮: 跨品类生态驱动的 '人-车-场' AI 全景体验新范式 Huaqin Galaxy: A Cross-Category Ecosystem Approach to Human-Cabin-Environment AI Experience	朱何安, 华勤技术股份有限公司, 产品战略总监 Eric AN, Product Strategy Director, Huaqin Technology Co., Ltd.

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## 2026（第四届）国际汽车电子技术创新论坛

### 2026 International Automotive Electronics Technology Innovation Forum

2026年7月2日 | N1馆 M42会议室（二楼）  
July 2, 2026 | Room M42 (2nd floor) in Hall N1

白金赞助:   黄金赞助:   

主题: 智能驾驶

Session: Intelligent Cockpit

主持人: 吕楠, 光庭信息, 全球市场及销售副总裁、德国光庭 CEO

Moderator: Nan Lv, Global Sales & Marketing VP, KOTEI CEO, KOTEI Germany

时间 Time	演讲主题 Topic	演讲企业 Speaker
09:30-10:00	签到入场 Registration	
10:00-10:30	Agent 范式对智能驾驶研发的影响 The Impact of the Agent Paradigm on Autonomous Driving R&D	殷玮, 智己汽车, 智驾中心软件总监 WEI YIN, Software Director, Intelligent Driving Center, IMMOTORS
10:30-11:00	英飞凌汽车中央架构雷达解决方案介绍 Infineon Automotive Raw-Satellite Radar Solution Introduction	王楠, 英飞凌科技, 汽车业务大中华区高级市场经理 Nigel Wang, Senior Marketing Manager of Infineon Technologies Automotive in Greater China
11:00-11:30	AI+ 车规级芯片失效分析 AI in Automotive Chip Failure Analysis	张林华, 胜科纳米(苏州)股份有限公司, 技术总监 Linhua Zhang, Technical Director, Wintech Nano (Suzhou) Co., Ltd
11:30-12:00	“车规级 SE + NFC: 一颗“安全芯”, 一把“数字钥”, 一触“万物联” Automotive-grade SE + NFC: One security chip, one digital key, one tap for full connectivity.	黄海明, 上海复旦微电子集团股份有限公司, 技术市场工程师 Haiming Huang, Technical Marketing Engineer, Shanghai Fudan Microelectronics Group Co., Ltd.

主持人: 卢万成, 上海浦东汽车电子创新与智能产业联盟专家委主任, 联合电子原副总工程师

Moderator: WanchengLu, Director of the Expert Committee, SPAEIA, Former Deputy Chief Engineer, UAES

时间 Time	演讲主题 Topic	演讲企业 Speaker
13:15-13:45	高性能毫米波雷达赋能安全驾驶 High-performance Millimeter-wave Radar Empowers Safe Driving	李鲁强, 上海保隆科技汽车股份有限公司, 总监 Leo Li, Director, Shanghai Baolong Automotive Corporation
13:45-14:15	携手打造智能出行 Architecting Trusted Intelligent Mobility Together	彭妙颜 Mieu-Ngan Pang, ADI 汽车业务生态与市场战略高级总监 Mieu Ngan Pang, Senior Director, Ecosystem Strategy and Marketing, Automotive, ADI
14:15-14:45	瑞萨电子赋能跨域融合与中央计算 Renesas Enhances Cross-domain Integration and Centralized Computing	杜维, 瑞萨电子, 汽车电子高级市场经理 Wei Du, Product Marketing Specialist, Renesas Electronics
14:45-15:15	使用正弦振幅转换器 (SACT™) 技术为面向未来的汽车实现高压到 SELV 转换 Future-Proof Automotive High-Voltage-to-SELV Conversion Using Sine Amplitude Converter (SACT™) Technology	毛敏, Vicor, 高级应用工程师 Mao Min, Senior FAE, Vicor
15:15-15:45	博世 MEMS 传感器丰富智驾选择 Bosch MEMS Sensor, Wide Offerings to ADAS	汪侃, 博世(中国)投资有限公司, 产品经理 Kan Wang, Product Manager, Bosch (China) Investment Ltd.
15:45-16:15	汽车智能化平台的分享与思考 Sharing and Reflections on Automotive Intelligence Platforms	吴庆文博士, 科博达技术股份有限公司, 高级工程师(教授级) Dr. Wu, Qingwen, Senior Director, Keboda Technology Co.,Ltd.

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The meeting agenda is subject to the announcement on the day.



## 2026 年国际电机驱动技术论坛

### International Motor Drive and Control Technology Forum 2026

2026 年 7 月 2 日 | N3 馆现场论坛区 (N3.379 展位)  
July 2, 2026 | On-site Forum Area in Hall N3 (Booth No. N3.379)

时间 Time	演讲主题 Topic	演讲企业 Speaker
09:30-10:00	观众签到 Register	
10:00-10:30	灵动微电子电机产品介绍暨家电、机器人市场拓展 Introduction to MindMotion Microelectronics' Motor Products and Market Expansion in Home Appliance & Robotics Sectors	雷江峰, 灵动微电子, 资深产品总监 Jacky Lei, Senior Product Director, MindMotion Microelectronic
10:30-11:00	恩智浦 MCU 赋能下一代边缘智能电机控制 NXP MCU Empowering Next-Gen Edge Intelligent Motion Control	罗嘉翔, 恩智浦, 大中华区市场经理 Jason Luo, Marketing Manager, Greater China, NXP
11:00-11:30	安森美面向汽车和工业电机驱动的智能功率模块 onsemi Intelligent Power Modules for Automotive and Industrial Motor Drive Applications	赵新壁, 安森美, 技术市场 Hank Zhao, Technical Marketing, onsemi
11:30-12:00	宽禁带半导体技术在电机驱动中的应用 Application of WBG Technology in Motor Drives	陈立烽, 英飞凌, 高级总监 Albert Chen, Senior Director, Infineon
时间 Time	演讲主题 Topic	演讲企业 Speaker
13:30-14:00	具身智能, 运控未来: 先楫赋能机器人核心运动 控制 Empowering Next-Generation Robotics with Advanced Motion Control	余国民, 先楫半导体, 北京先楫机器人副总经理 Martin Yu, HPMicro Robotics Semiconductor Technology Co., Ltd., HPMicro
14:00-14:30	ADI Trinamic 运动控制新产品介绍 ADI Trinamic Motion Control New products Introduce	高伟, ADI Trinamic 产品线经理 Gavy Gao, ADI Trinamic Product Line Manager
14:30-15:00	纳芯微 NSSine™ 系列实时控制 MCU/DSP- 产品 核心性能和生态解析 NSSine™ Real-time Microcontrollers (MCUs)/DSPs: Key Performance Features and Ecosystem Insights	张炎, 纳芯微电子, 产品经理 William Zhang, Product Manager, NOVOSENSE Microelectronics
15:00-15:30	STM32 整合电机控制平台 STM32 rebuild motor control platform	卢永海, 意法半导体, MCU 中国市场经理 Senior Manager of Microcontroller Microprocessor Marketing, Greater China, ST Microelectronics

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## 全球电子元器件供需对接峰会

### Supplyframe Global Electronic Components Sourcing & Supply Summit

2026 年 7 月 2 日 | N1 馆 M40 会议室 (一楼)  
July 2, 2026 | Room M42 (2nd floor) in Hall N1

时间 Time	演讲主题 Topic	演讲企业 Speaker
10:00-10:10	开场 Opening & Welcome	四方维行业分析师 Industry Analyst, Supplyframe
10:10-10:30	西门子电子制造供应链分享 Siemens Electronics Manufacturing Supply Chain Insights	Sophia Shi, 西门子, Regional Commodity Manager Sophia Shi, Regional Commodity Manager, Siemens
10:30-10:50	芯耀计划: 国产芯全球通路 Atlas Project: Global Channels for Chinese Chips	郝天涯, 四方维, 市场拓展经理 Vicky Qie, Business Development Manager, Supplyframe
10:50-11:10	全球格局重塑下的供应链转型—亚太机遇、ESG 驱 动与中国企业出海 Reshaping Global Supply Chains: APAC Opportunities, ESG Dynamics, and Global Expansion of Chinese Enterprises	蒋文辉, 欧时中国, 商务发展和市场总监 Wendy Jiang, BD & Marketing Director, RS China
11:10-11:30	电子元器件供应链数字化的探索与实践 Exploration and Practice of Electronic Component Supply Chain Digitalization	马骏, 云汉芯城, KA 业务部商务总监 Jun Ma, Commercial Director of KA Business Dept, Unikey
时间 Time	演讲主题 Topic	演讲企业 Speaker
14:00-14:30	圆桌论坛 Panel Discussion	Sophia Shi, 西门子, Regional Commodity Manager (拟邀) Sophia Shi, Regional Commodity Manager, Siemens 郝天涯, 四方维, 市场拓展经理 Vicky Qie, Business Development Manager, Supplyframe 张宇, 四方维, SaaS 售前顾问 Vincent Zhang, Pre-Sales Consultant (SaaS), Supplyframe
14:30-14:50	教育硬件出海: 中国技术创新与全球市场机遇 Educational Hardware Expansion: Chinese Innovation Meets Global Opportunities	夏青, 上海智位机器人股份有限公司, 高级工程师、 蘑菇云创客空间联合创始人 Qing Xia, Senior Engineer at DFRobot & Co- founder of Mushroom Cloud Maker Space
14:50-15:10	从缺料到韧性: 2026 PCB 供应链现状与企业应对 策略 Building PCB Supply Chain Resilience in 2026: Challenges & Response Strategies	张建波, NCAB 集团, 品质与技术经理 Zero Zhang, Quality and Technical Manager, NCAB Group
15:10-15:30	从选型到绿色合规, XQ 与 XQ-ECO2 构建绿色供 应链管理 From Component Selection to Green Compliance: Structuring Sustainable Supply Chains with XQ & XQ-ECO2	张宇, 四方维, SaaS 售前顾问 Vincent Zhang, Pre-Sales Consultant (SaaS), Supplyframe
15:30-15:50	企业出海 - 金融赋能 共创未来 Going Global: Financial Empowerment for a Shared Future	陈晨, 西门子金融服务, 中国战略发展总监 Chen Chen, Strategy Development Director of Siemens Financial Services China

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## 具身智能产业应用大会

### Embodied AI Industry Application Conference

2026年7月1日 | W4 馆现场论坛区 (W4.671 展位)  
July 1, 2026 | On-site Forum Area in Hall W4 (Booth No.W4.671)

时间 Time	演讲主题 Topic	演讲企业 Speaker
09:30-09:35	开幕致辞 Opening Ceremony Speech	罗瑞洋, 慕尼黑展览(上海)有限公司, 首席财务官兼副总经理 Jan Rohde, CFO & Deputy General Manager, Messe Muenchen Shanghai Co., Ltd.
09:35-09:40	连界创新具身智能中心开幕致辞 Innolink Opening Ceremony Speech	沈苏怡, 北京连界创新技术股份有限公司, 具身智能中心合伙人 Suzy Shen, Co-partner, Beijing Innolink Technology Co., Ltd
09:40-10:00	主题演讲 1: 《具身智能机器人产品打造及场景实践》 Product Development and Scenario-based Implementation of Embodied Intelligent Robots	黄庭, 中移(杭州)信息技术有限公司, 具身智能产品部副总经理 Huang Ting, Deputy General Manager, Embodied Intelligence Product Department, China Mobile (Hangzhou) Information Technology Co., Ltd.
10:00-10:20	主题演讲 2: 《具身智能生态, 重塑下一代生产力》 Embodied Intelligence Ecosystem   Reshaping Future Productivity	仓玉, 银河通用机器人股份有限公司工业事业部总裁 Cang Yu, President, Industrial Division, Beijing Galbot Co., Ltd.
10:20-10:40	主题演讲 3: 《具身智能的“水电煤”: 端云一体的计算基础设施》 Foundational Infrastructure for Embodied AI: Converged Edge-Cloud Computing	江舟, 地瓜机器人, 销售副总裁 Jonathan, Vice President of Sales, D-Robotics
10:40-11:00	主题演讲 4: 《RISC-V 实时 DSP: 小体积强算力快响应-低发热——芯破局, 重构关节性能边界》 Compact, Powerful, Rapid Response, Low Thermal Output	徐勇, 广东匠芯创科技有限公司, 市场总监 Xu Yong, Marketing Director, Guangdong ArtInChip Technology Co., Ltd.
11:00-11:20	主题演讲 5: 《超越自由度: 重新思考面向真实世界部署与 UMI 的灵巧手设计》 Beyond Degrees of Freedom: Reimagining the Design of Dexterous Hands for Real-World Deployment and UMI Applications	王乐天, 北京星动纪元科技股份有限公司, 产品副总裁 Letian (Lucas) Wang, VP of Product, Beijing Xingdongjiyuan Co., Ltd.
11:20-11:40	主题演讲 6: 《聚焦主动交互, 做以人为本的具身智能》 Human-Centered Embodied Intelligence Through Proactive AI	翟彦祺, 上海傅利叶智能科技股份有限公司, 副总裁 Willys Zhai, VP, Fourier Intelligence Inc.
11:40-12:00	主题演讲 7: 《智赋智造: 具身机器人重构工业自动化新范式》 Intelligent Manufacturing: Embodied Robotics Drive a New Era of Automation	尉斗南, 宁波均普智能制造股份有限公司, 具身事业部商业及战略发展副总裁 Dounan Yu, Vice President, Commercial & Strategic Development, Embodied AI Business Unit, Ningbo PIA Automation Holding Corp.

时间 Time	演讲主题 Topic	演讲企业 Speaker
13:00-13:20	主题演讲 1: 《迈向通用机器人的人机曙光时刻》 The dawn of universal humanoid robots is approaching	徐国强, 千寻智能, 销售总监 Viery Xu, Sales Director, Spirit-AI
13:20-13:50	主题演讲 2: 《一站式系统级方案, 赋能 AMR 从智能感知到精准控制》 AMR System-Level Solution: Empowering End-to-End Innovation from Intelligent Sensing to Efficient Motion Control	杨正龙, onsemi, 亚太区市场经理 Henry Yang, APGC regional Marketing, onsemi
13:50-14:20	主题演讲 3: 《迈来芯位置传感器在具身智能领域的解决方案》 Melexis Position sensor solution for Humanoid application	方义岳, 迈来芯电子科技(上海)有限公司, 市场经理 Eamon Fang, Regional Marketing Manager, Melexis
14:20-14:50	主题演讲 4: 《InnoGaN 机器人芯动力》 InnoGaN: Core Power for Robotics	孟无忌, 英诺赛科(苏州)科技股份有限公司, 产品应用经理 Eric Meng, AE manager, Innoscience
14:50-15:20	主题演讲 5: 《以触觉与灵巧操作智能推动机器人走向通用》 Advancing robots toward general intelligence through tactile sensing and dexterous manipulation	吴海滔, 戴盟(深圳)机器人科技有限公司, 业务拓展总监 Haitao Wu, Business Development Director, Daimon (Shenzhen) Robotics Technology Co., Ltd.
15:20-15:50	主题演讲 6: 《ADI 技术助力人形机器人创新发展》 Driving Humanoid Robotics Innovation with ADI Technologies	张一峰, ADI 中国区工业自动化行业产品市场经理 Paul Zhang, Product Marketing Manager of ADI China
15:50-16:10	主题演讲 7: 《AI 嗅觉感知芯片赋能智能体进入千家万户》 AI Olfactory Sensing Chips Empower Agents to Reach Every Household	张含波, 深圳市亿思迈科技有限公司, 首席执行官 HANBO/ZHANG, Easemell Technology (Shenzhen) Limited, CEO
16:10-16:30	主题演讲 8: 《面向量产时代的具身智能基础设施实践》 Embodied Intelligence Infrastructure Practices for the Mass Production Era	孙颖欣, 百度智能云, 泛科技行业解决方案总监 Yingxin Sun, Director of Pan-Tech Industry Solutions, Baidu Intelligent Cloud

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## 具身智能产业应用大会

### Embodied AI Industry Application Conference

2026年7月2日 | W4馆现场论坛区 (W4.671展位)

July 2, 2026 | On-site Forum Area in Hall W4 (Booth No.W4.671)

时间 Time	演讲主题 Topic	演讲企业 Speaker
09:30-09:50	主题演讲 1: 驱动具身智能加速走入工业场景 Accelerating the Implementation of Embodied Intelligence in Industrial Scenarios	陈超, 西门子, 工业 AI 高级专家 Benson Chen, Senior Industry AI Expert, Siemens
09:50-10:10	主题演讲 2: 《向险而行 向新而生——赋能千万个高危场景》 Facing Danger, Embracing Renewal — Empowering Millions of High-Risk Scenarios	黄子炎, 具微科技, 首席营销官 Ares, CMO, MICBOT
10:10-10:40	主题演讲 3: 《算力控运动, 安全守整机   国民技术——构建机器人运动控制全链路芯片解决方案》 Compute for Motion, Security for Integrity NSING:Full-Chain Chip Solutions for Robot Motion Control	冉瑞宝, 国民技术股份有限公司, 高级产品经理 Ruibao Ran, Senior Product Manager, NSING TECHNOLOGIES INC.
10:40-11:00	主题演讲 4: 《人工智能时代机器人的魅力和可能》 The charm and possibilities of robots in the era of artificial intelligence	陈君, 上海触碰未来机器人有限公司, 联合创始人 Harry, Co-founder/Deputy General Manager, Shanghai Touch Future Robot Co., Ltd
11:00-11:20	主题演讲 5: 《以仿人化能力链接工业、医疗与消费的未来》 Humanoid Capabilities Connect the Future of Industry, Healthcare and Consumption	殷佳俊, 上海非夕机器人科技, 新市场总监 Jiajun Yin, New Market Business Director Shanghai Flexiv Robotics
11:20-11:40	主题演讲 6: 《以手赋能 以量破局: 定义灵巧手产业化新范式》 《Performance & Mass Production: Reshaping Dexterous Hand Industry》	房海南, 因时机器人, 首席营销官 Hannah Fang, CMO, Beijing Inspire Robots Technology CO.,LTD

时间 Time	演讲主题 Topic	演讲企业 Speaker
13:00-13:30	主题演讲 1: 《具身智能领域被证实有效的工程链路——全身运动控制和遥操作行为克隆》 Proven Engineering Pipelines in Embodied Intelligence — Whole Body Control and Teleoperation Behavior Cloning	尹富珑, 艾欧智能(深圳)有限公司, 华东区总经理兼运控研发总监 Yin Fulong, Manager of East China & Director of Humanoid Locomotion R&D, IO-AI Tech
13:30-14:00	主题演讲 2: 《世界模型 + 多智能体的未来》 The Future of World Models and Multi-Agents	吴国宁, 超脑未来(深圳)科技有限责任公司, 创始人 Guoning Wu, Founder, World Agents
14:00-14:30	主题演讲 3: 《场景数据模型: 具身智能的飞轮效应》 Scenarios, Data, and Models: Building the Flywheel of Embodied Intelligence	刘佳, 晨昏线科技, 晨昏线科技联合创始人兼 CEO Julian Liu, Co-founder and CEO of Termitech, Termitech
14:30-15:00	主题演讲 4: 《物理 AI 数据基座 —— 赋能具身智能机器人商业化落地与产业》 Physical AI Data Infrastructure - Enabling the Commercial Deployment and Industrialization of Embodied Intelligent Robots	严玮, 北京无问智行科技有限公司, 解决方案专家 Yan Wei, Solutions Specialist, Wuwen-ai Co.,ltd
15:00-15:30	主题演讲 5: 《动见全域空间 - 视觉原生驱动捕驱人形机器人自主进化》 Full-Space Perception: Vision-Native Motion Capture Drives Autonomous Evolution of Humanoid Robots	王占魁, 北京动见万物科技有限公司, CMO Wang Zhankui, CMO, Dong Think
15:30-16:00	主题演讲 6: 《AI 驱动的多物理场仿真训练系统加速产业化应用》 AI Agent powered Multi-physics Simulation Platform accelerates Physical AI Application	张小波, 上海松应科技, 联合创始人 Xiaobo Zhang, Co-Founder & Chief Product Officer, Shanghai Songying Technology
16:00-16:30	主题演讲 7: 《本能驱动: 重构通用具身操作的底层逻辑》 Instinct-Driven: Redefining the Underlying Logic of General Embodied Manipulation	姜晓, 橡木果, 橡木果发起人 Jiang Yao, Initiator, Acorn Robot

07/01

## 国际连接器创新论坛

## International Connector Innovation Forum

2026年7月1日 | W3 馆现场论坛区 (W3.659 展位)  
July 1, 2026 | On-site Forum Area in Hall W3 (Booth No.W3.659)

白金赞助:



黄金赞助:



上午主题: 连接器行业设计、材料、工艺、检测、标准等基础共性技术研究

AM Session: Research on Connector Basic Generic Technologies, Such as Design, Materials, Processes, Testing, and Standards

主持人: 许良军, 北京邮电大学, 教授

Moderator: Liangjun Xu, Professor, Beijing University of Posts and Communications

时间 Time	演讲主题 Topic	演讲企业 Speaker
09:30-09:45	签到入场 Registration	
09:45-10:15	AI 时代的电连接技术 Electrical Connection Technology in the AI Era	许良军, 北京邮电大学, 教授 Liangjun Xu, Professor, Beijing University of Posts and Telecommunications
10:15-10:45	智连与智材: AI 算力时代下高速连接器与高性能铜合金的协同创新 Intelligent Connectivity & Intelligent Material	张敏, 宁波博威合金材料股份有限公司, 技术市场部总监 Jason ZHANG, Director, Technical Marketing Dept., Ningbo Boway Alloy Material Co., Ltd.
10:45-11:15	高性能铜合金助力 AI 时代的数据互联与热管理 High-Performance Copper Alloys for Data Interconnects and Thermal Management in the AI Era	陈永满, 兴业合金材料集团有限公司, 高级研发经理 Yongman Chen, Senior R&D Manager, Xingye Alloy Materials Group Co., Ltd.
11:15-11:45	智能互联时代下铜合金带材的战略价值 The Strategic Importance of Copper Alloy Strips in the Age of Smart Connectivity	陈继田, 宁波金田铜业(集团)股份有限公司, 研发经理 Chen Jitian, R&D Manager, Ningbo Jintian Copper (Group) Co., Ltd.
11:45-12:15	铜合金新产品开发 New Product Development of Copper Alloys	陈希春博士, 浙江国工新材料技术开发有限公司, 董事长 Chen Xichun, Chairman of the Board, ZHEJIANG METAL MASTER TECHNOLOGY CO.,LTD

下午主题: 连接器技术趋势和发展

PM Session: Development Trend of Connector

主持人: 彭永权博士, 台湾电子连接产业协会, 秘书长

Moderator: YUNG CHUAN PENG, Secretary General, Taiwan Electronic Connector Association (TECA)

时间 Time	演讲主题 Topic	演讲企业 Speaker
13:30-14:00	“大动脉”与“守护者”: 泰科电子全新一代安全连接技术发布 Launch of TE Connectivity's New-Generation Safety Connection Technology	李兴琢, 泰科电子, 汽车事业部中国区产品管理高级经理 Michael Li, Sr Manager, Product Management, TE Connectivity Automotive China
14:00-14:30	商业航天星载高速互连的发展与思考 Development and Reflections on Onboard High-Speed Interconnection for Commercial Spacecraft	王勇, 贵州航天电器股份有限公司, 上海研究院副院长 Lance Wang, senior engineer, Guizhou Space Appliance Co.,LTD.
14:30-15:00	盲插架构液冷服务器流体连接器解决方案 Solution for blind plug architecture liquid cooled server fluid connector	李俊阳, 中航光电科技股份有限公司, 高级工程师 Li Junyang, Senior Engineer, JONHON Optronic Technology Co., Ltd.
15:00-15:30	超节点 224G 高速互联系统方案实践与思考 Practice and Thinking on the 224G High-Speed Interconnection System Scheme for Super Nodes	陈宣豪, 庆虹电子(苏州)有限公司, 产品总监 Arthur Chen, Product director, Qinghong electronics (suzhou) co.,ltd.
15:30-16:00	智能座舱座椅的连接器技术现状与演进 The Current Status and Evolution of Connector Technology for Automotive Intelligent Cabin Seats	陈加云, 李尔公司, 连接器研发经理 Chen Jiayun, Engineering Manager, Connections Systems, Lear Corporation
16:00-16:30	实体 AI 浪潮下的连接革命 The Connection Revolution under the Wave of Embodied AI	彭永权博士, 台湾电子连接产业协会, 秘书长 Dr.YUNG CHUAN PENG, Secretary General, Taiwan Electronic Connector Association (TECA)

\*会议日程请以当天公告为准

The meeting agenda is subject to the announcement on the day.

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## 国际连接器创新论坛

## International Connector Innovation Forum

2026年7月2日 | W3 馆现场论坛区 (W3.659 展位)  
July 2, 2026 | On-site Forum Area in Hall W3 (Booth No.W3.659)

白金赞助:



黄金赞助:



上午主题: 连接器行业设计、材料、工艺、检测、标准等基础共性技术研究

AM Session: Latest Development of Connector Basic Generic Technologies, Such as Design

主持人: 周明亮, 深圳市连接器行业协会, 材料中心主任

Moderator: Michael ZHOU, Executive Director of the Materials Center, Shenzhen Connector Industry Association

时间 Time	演讲主题 Topic	演讲企业 Speaker
09:30-10:00	签到入场 Registration	
10:00-10:30	算力与 AI 浪潮下连接器原材料的变革和机遇 Changes and Opportunities for Connector Raw Materials in the Computing Power Revolution and AI Wave	周明亮, 深圳市连接器行业协会, 材料中心主任 Michael ZHOU, Executive Director of the Materials Center, Shenzhen Connector Industry Association
10:30-11:00	智能化驱动下鑫科的产品方案 Intelligent-Driven Product Solutions from Xinke	钮松博士, 安徽鑫科新材料股份有限公司, 技术中心主任 Song Niu, Director of Technology Center, ANHUI XINKE NEW MATERIALS CO., LTD.
11:00-11:30	世索科在 AI 数据中心连接器的材料解决方案 Syensqo solutions for AI datacenter connectors	葛婷婷, 世索科, 市场经理 Tina Ge, Marketing Manager, Syensqo
11:30-12:00	复合金属材料发展与在连接器行业的应用 Development of Composite Metal Materials and Their Application in the Connector Industry	邱文婷博士, 深圳市中金岭南科技有限公司, 复合材料研发中心主任, 高级工程师 Qiu Wenting, Senior Engineer, Shenzhen Nonfemet Technology Co., Ltd

下午主题: 连接器技术趋势和发展

PM Session: Development Trend of Connector

主持人: 谭宇, TVM 全面价值管理协会, 秘书长

Moderator: Ryan Tan, Secretary-General, TVM Total Value Management Association

时间 Time	演讲主题 Topic	演讲企业 Speaker
13:30-14:00	智造连接 --AI 如何重塑连接器制造新范式 Intelligent Manufacturing Connection-- How AI Is Reshaping a New Paradigm in Connector Manufacturing	吴凤占, 采埃孚亚太汽车安全系统上海有限公司, 工程经理 Franklin Wu, Engineering Manager, ZF Asia Pacific Automotive Safety Systems (Shanghai) Co., Ltd.
14:00-14:30	车载低压连接器技术趋势及安波福系统解决方案 Powering the Future: Low-Voltage Connector Innovations & Aptiv System Solutions	赵延, 安波福中央电气(上海)有限公司, 产品经理 Ked Zhao, Product Line Manager, Aptiv Electrical Centers (Shanghai) Co., Ltd.
14:30-15:00	速赢未来, 高效 PCB 连接器接线技术和安装工艺 Get future by speed & efficiency, Efficient Wiring Technologies and Assembly Processes of PCB Connectors	刘新, 菲尼克斯电气中国公司, 产品经理 Xin LIU, Product manager, Phoenix Contact China
15:00-15:30	电动车高速连接器的应用 High-speed connector application in EV	孙新彪, 某整车厂, 研发经理 XinbiaoSun, head of COE team, OEM
15:30-16:00	汽车新能源时代的连接器创新技术应用研究 Application of Advanced Connector Technologies in the NEV Era	谭宇, TVM 全面价值管理协会, 秘书长 Ryan Tan, Secretary-General, TVM Total Value Management Association

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## 智能联接，协同进化：下一代柔性技术赋能智慧工厂

### Intelligent Connectivity, Co-evolution: Empowering Smart Factories with Next-Generation Flexible Technology (Industrial Connectors)

2026年7月2日 | W2馆 M9会议室 (二楼)  
July 2, 2026 | Room M9 (2nd floor) in Hall W2

时间 Time	演讲主题 Topic	演讲企业 Speaker
09:00-10:00	签到 / 嘉宾入场 Sign-in / Guest Entry	
10:00-10:30	前瞻洞察引领，敏捷创新驱动 施耐德电气以数字化优势赋能智慧工厂 Foresight-Driven, Agile Innovation: Schneider Electric Empowers Smart Factories with Digital Advantages	潘知翼，施耐德电气（中国）有限公司，解决方案总监 Zhiyi Pan, Solution Director, Schneider Electric (China) Co., Ltd.
10:30-11:00	800V 高压直流浪潮下，连接器工程塑料是否会成为系统保护的最后一块短板？ 800V HVDC is coming, is your power connector reliable?	谢建志，恩骅力工程材料，全球行业创新经理 John Hsieh, Segment Innovation Manager, Envalior Engineering Materials
11:00-11:30	工业连接器创新：赋能柔性制造的可靠联接解决方案 Industrial Connector Innovation: Reliable Connectivity Solutions Empowering Flexible Manufacturing	刘鹏，泰科电子，TE Connectivity 重点行业 BU Liu Peng, Key Account BU, TE Connectivity
11:30-12:00	AI 赋能工业机器人：重构智能制造的柔性生产力 AI Empowering Industrial Robots: Reconstructing Flexible Productivity for Smart Manufacturing	陈英伟，翼菲机器人是浙江翼菲智能科技有限公司，技术总监 Chen Yingwei, Technical Director, Robotphoenix Intelligent Technology Co., Ltd
12:00-13:00	午餐 / 观展 / 午后嘉宾签到入场 Lunch / Exhibition Viewing / Afternoon Guest Check-in and Entry	

时间 Time	演讲主题 Topic	演讲企业 Speaker
13:00-13:00	签到 / 嘉宾入场	
13:00-13:30	协作机器人从安全角度重构产线概念 Collaborative robots are redefining production line concepts from a safety perspective	阮胜，遨博（北京）智能科技股份有限公司，行业总监 Ruan Sheng, Industry Director, AUBO (BEIJING) ROBOTICS TECHNOLOGY CO., LTD
13:30-14:00	从微小连接器设计到高可靠自动化组装：I-PEX 如何协助客户提升量产稳定性与组装良率 From Connector Design to Automated Assembly: How I-PEX Supports Stable Mass Production of Micro Connectors	王友千，爱沛电子，I-PEX CARA Lab 负责人 / 微小连接器自动化组装解决方案专家 Kenny Wang, I-PEX CARA Lab leader / Micro Connector Automated Assembly Solution Expert, I-PEX
14:00-14:30	从快换到柔性：连接器如何支撑 AI 时代的敏捷生产需求 From quick-change to flexibility: How connectors support agile production requirements in the AI era	邓文锋，浩亭（珠海）贸易有限公司，浩亭产品应用总监 Daniel Deng, Head of Technical Application Consultant, HARTING (Zhuhai) Sales Ltd.
14:30-15:00	魏德米勒在 SPE 赋能工业智能化上的探索 Industrial Intelligence empowered by SPE technology	杨超操，魏德米勒电联接（上海）有限公司，魏德米勒亚太区工业连接器事业部总监 Andy Yan, Director-Division Device & Field Connectivity Asia Region, Weidmüller Interface (Shanghai) Co., Ltd.
15:00-15:30	“AI+ 安全”双核引领，护航工业智造全场景 Driven by Both "AI + Security", Safeguarding All Scenarios of Industrial Smart Manufacturing	朱辰杰，深圳市湾测技术有限公司，销售副总监 Zhu Chen Jie, Sales Deputy Director, Shenzhen Wonsor Technology Co., Ltd
15:30-16:00	海康机器人“眼脚手”协同智慧工厂智造升级 Hikrobot's "Eye-Hand-Support" Collaborative Smart Factory for Intelligent Manufacturing Upgrade	王瀛，杭州海康机器人股份有限公司，行业总监 Wang Ying, Industry Director, Hangzhou Hikrobot Co., Ltd
16:00-17:00	观展 / 现场交流 Exhibition Tour	

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## 东莞企业新品发布会 Dongguan Enterprise New Product Launch

2026年7月2日 | W3-M10 会议室  
July 2, 2026 | Room M10 (2nd floor) in Hall W3

时间 Time	演讲企业 Speaker
10:20-10:30	签到入场 Check-in and socializing
10:30-10:35	主持人介绍出席活动的领导和重要嘉宾 Introduction to the leaders and important guests present at the event
10:35-10:40	东莞市商务局领导致辞 Speech by the leader of Dongguan Municipal Bureau of Commerce
10:40-10:45	东莞展商代表致辞 Speech by the representative of Dongguan exhibitors
10:45-11:40	行业领先企业优势产品发布 Launch of superior products of industry-leading enterprises
10:45-10:55	广东黄宝石电子科技有限公司 GuangDong TOPAZCON Electronic Technology Co.,Ltd
10:55-11:05	优利德科技(中国)股份有限公司 UNI-TREND TECHNOLOGY (CHINA) CO., LTD.
11:05-11:15	东莞市钿威电子科技有限公司 DONGGUAN DIANWEI ELECTRONIC TECHNOLOGY CO., LTD
11:15-11:25	东莞市刘氏电子有限公司 DONG GUAN LIUSHI ELECTRONICS CO., LTD
11:25-11:35	东莞市三瑞自动化科技有限公司 Dongguan Sunrise Automation Co., Ltd.
11:35-11:45	广东科尼盛电子科技有限公司 GUANGDONG KNSCHA ELECTRONICS CO., LTD
11:50-12:00	自由交流 Free communication

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|---|---------------|--|---------------|
| <span style="color: green;">■</span> 连接器、开关、线束线缆<br>Connectors, Switches, Cable Harness | <b>W1-W4</b>  | <span style="color: pink;">■</span> 传感器<br>Sensors                               | <b>N3</b>     |
| <span style="color: yellow;">■</span> 电源<br>Power Supplies                              | <b>W5</b>     | <span style="color: lightblue;">■</span> 半导体制造与测试<br>Semiconductor Manufacturing | <b>N3</b>     |
| <span style="color: blue;">■</span> 电子测试测量<br>Test & Measurement                        | <b>W5</b>     | <span style="color: darkgreen;">■</span> 印刷电路板<br>PCB<br>电子制造服务<br>EMS           | <b>N3, W4</b> |
| <span style="color: brown;">■</span> 分销商<br>Distributors                                | <b>W5, N2</b> | <span style="color: purple;">■</span> 半导体<br>Semiconductors                      | <b>N3-N5</b>  |
| <span style="color: orange;">■</span> 无源器件<br>Passive Components                        | <b>N1-N2</b>  | <span style="color: magenta;">■</span> 嵌入式<br>Embedded System                    | <b>N5</b>     |
| <span style="color: red;">■</span> 显示<br>Display  | <b>N1</b>     |  |               |
| <span style="color: darkred;">■</span> 元器件制造<br>Component Manufacturing                 | <b>N2</b>     |  |               |

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# 明年4月见

2027年4月14-16日

上海新国际博览中心

展会联系:

邱女士/Ms.Chloe Qiu

021-20205522

chloe.qiu@mm-sh.com



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